



TABLE 1

POLES	DIMENSIONS (mm)		
	A	B	C
2*02	1.27	2.54	
2*03	2.54	3.81	1.27
2*04	3.81	5.08	2.54
2*05	5.08	6.35	3.81
2*06	6.35	7.62	5.08
2*07	7.62	8.89	6.35
2*08	8.89	10.16	7.62
2*09	10.16	11.43	8.89
2*10	11.43	12.70	10.16
2*11	12.70	13.97	11.43
2*12	13.97	15.24	12.7
2*13	15.24	16.51	13.97
2*14	16.51	17.78	15.24
2*15	17.78	19.05	16.51

NOTES: UNLESS OTHERWISE SPECIFIED

- ALL DIMENSIONS ARE IN MILLIMETER, PER ASME Y14.5M-2009.
- ELECTRICAL CHARACTERISTICS:
 - 2-1 VOLTAGE RATING: 125 VAC MAX..
 - 2-2 CURRENT RATING: 1.0 A MAX. PER PIN, 30°C RISE ABOVE AMBIENT.
 - 2-3 CONTACT RESISTANCE: 20 MILLIOHMS MAX. FOR INITIAL, 40 MILLIOHMS MAX. AFTER TEST.
 - 2-4 DIELECTRIC WITHSTANDING VOLTAGE: 500V AC R.M.S..
 - 2-5 INSULATION RESISTANCE: 1000 MEGOHMS MIN..
- OTHER CHARACTERISTICS:
 - 3-1 THE PRODUCT WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION INFRA-RED OR VAPOR PHASE REFLOW OVEN.
 - 3-2 PRODUCT SPEC: GS-12-629.
 - 3-3 MATE WITH: 10165448.

10166143 - 0 0 X XX X X LF

POST OPTION
 0: WITHOUT POST
 1: WITH POST

PIN COUNT
 SEE TABLE 1
 04: 2*02

 30: 2*15

LEAD FREE
 PLATING
 1: GOLD FLASH ALL OVER
 2: 0.76µm GOLD ON CONTACT AREA
 2.54µm TIN ON SOLDER AREA
 0.76µm NICKEL UNDER PLATED

PACKING
 C: TAPE REEL WITH CAP

3	CONTACT	COPPER ALLOY	0.76µm MIN. NICKEL PLATING OVERALL UNDERPLATED 2.54µm MIN. TIN OR G/F PLATING OVER NICKEL AT TAIL GOLD PLATING ON CONTACT AREA
2	HOUSING	THERMOPLASTIC UL 94V-0	MOLDED BLACK
1	CAP	THERMOPLASTIC UL 94V-0	MOLDED BLACK
ITEM	DESCRIPTION	MATERIAL	TREATMENT
mat'l. code		surface ISO 1302 ✓	tolerance ISO 406 ISO 1101
ltr ecn no dr		tolerances unless otherwise specified	
A	- SANFORD LIU 05/29/23	angles	0.X±0.30
B	ELX-N-291051 GRACE LIU 03/20/26	linear	0.XX±0.20
		0°±2'	0.XXX±0.10
		dr	GRACE LIU 03/20/26
		enr	GRACE LIU 03/20/26
		chr	L-Q LEI 03/20/26
		appd	TIM YAO 03/20/26
sheet index	revision sheet	B	
	1		
product family		HPL 585	
title		MINITEK 1.27	
dwg no		sheet 1 of 1	size
10166143			A3
type		Product Customer	Drawing